AMENDMENTS TO THE CLAIMS

Please replace the pending claims with the following claim listing:

1-49. **(Canceled)**

- 50. **(Currently Amended)** A nitride semiconductor structure comprising on a substrate: an n-type collector layer;
- a p-type base layer formed over said n-type collector layer, wherein said p-type base layer is p-type InGaN;

an n-type emitter layer formed over directly on said p-type base layer;

an indium-containing p-type nitride semiconductor layer formed directly on said p-type base layer so as to contact a top surface of said p-type base layer, the top surface having been exposed by etching said n-type emitter layer, wherein said indium-containing p-type nitride semiconductor layer is regrown on said top surface does not contact said n-type emitter layer; and

a base electrode formed over said indium-containing p-type nitride semiconductor layer.

51. **(Currently Amended)** The nitride semiconductor structure according to claim 50, wherein said indium-containing p-type nitride semiconductor layer is p-type InGaN.

52. (Canceled)

- 53. **(Original)** The nitride semiconductor structure according to claim 51, wherein said ptype InGaN base layer has an indium mole fraction of 5 30%.
- 54. **(Currently Amended)** The nitride semiconductor structure according to claim 51, wherein said <u>indium-containing</u> p-type nitride semiconductor layer has an indium mole fraction higher than an indium mole fraction of said p-type InGaN base layer.

55. (Canceled)

- 56. **(Original)** The nitride semiconductor structure according to claim 55, wherein said ptype InGaN base layer has an indium mole fraction of 5 30%.
- 57. **(Currently Amended)** The nitride semiconductor structure according to claim 55, wherein said <u>indium-containing</u> p-type nitride semiconductor layer has an indium mole fraction higher than an indium mole fraction of said p-type InGaN base layer.
- 58. **(Original)** The nitride semiconductor structure according to claim 50, wherein said ptype InGaN base layer has an indium mole fraction of 5 30%.
- 59. **(Currently Amended)** The nitride semiconductor structure according to claim 58, wherein said <u>indium-containing</u> p-type nitride semiconductor layer has an indium mole fraction higher than an indium mole fraction of said p-type InGaN base layer.
- 60. (Currently Amended) The nitride semiconductor structure according to claim 50, wherein said <u>indium-containing</u> p-type nitride semiconductor layer has an indium mole fraction higher than an indium mole fraction of said p-type InGaN base layer.

61-76. (Canceled)

- 77. **(Previously Presented)** The nitride semiconductor structure according to claim 50, further comprising a graded layer between said p-type base layer and said n-type collector layer, wherein said graded layer has an indium mole fraction that varies gradually.
- 78. (**Previously Presented**) The nitride semiconductor structure according to claim 51, further comprising a graded layer between said p-type base layer and said n-type collector layer, wherein said graded layer has an indium mole fraction that varies gradually.

- 79. **(Previously Presented)** The nitride semiconductor structure according to claim 55, further comprising a graded layer between said p-type base layer and said n-type collector layer, wherein said graded layer has an indium mole fraction that varies gradually.
- 80. (Currently Amended) The nitride semiconductor structure according to claim 50, wherein the base electrode is formed directly on said indium-containing p-type nitride semiconductor layer.
 - 81. **(Currently Amended)** A nitride semiconductor structure comprising: an n-type collector layer;

a p-type base layer formed over said n-type collector layer, wherein the p-type base layer has an etched top surface and is p-type InGaN;

an n-type emitter layer formed over directly on said p-type base layer;

an indium-containing p-type nitride semiconductor layer formed directly on the etched top surface of the p-type base layer, wherein said indium-containing p-type nitride semiconductor layer does not contact said n-type emitter layer; and

a base electrode formed over said indium-containing p-type nitride semiconductor layer.

82. **(Previously Presented)** The nitride semiconductor structure according to claim 81, wherein said indium-containing p-type nitride semiconductor layer comprises p-type InGaN.

83. (Canceled)

- 84. **(Currently Amended)** The nitride semiconductor structure according to claim [[83]] 81, wherein said indium-containing p-type nitride semiconductor layer has an indium mole fraction higher than an indium mole fraction of said p-type base layer.
- 85. **(Previously Presented)** The nitride semiconductor structure according to claim 81, further comprising a graded layer between said p-type base layer and said n-type collector layer.

- 86. **(Currently Amended)** The nitride semiconductor structure according to claim 50, wherein [[the]] <u>said indium-containing</u> p-type nitride semiconductor layer has a thickness of between 1 and 1000 nm.
- 87. **(Currently Amended)** The nitride semiconductor structure according to claim 50, wherein [[the]] <u>said indium-containing</u> p-type nitride semiconductor layer has a thickness of about 100 nm.
- 88. **(Currently Amended)** The nitride semiconductor structure according to claim 81, wherein [[the]] <u>said indium-containing</u> p-type nitride semiconductor layer has a thickness of between 1 and 1000 nm.
- 89. **(Currently Amended)** The nitride semiconductor structure according to claim 81, wherein [[the]] <u>said indium-containing</u> p-type nitride semiconductor layer has a thickness of about 100 nm.
 - 90. **(New)** A nitride semiconductor structure comprising on a substrate: an n-type collector layer;
 - a p-type base layer formed over said n-type collector layer, wherein said p-type base layer is p-type InGaN;

an n-type emitter layer formed over said p-type base layer;

an indium-containing p-type nitride semiconductor layer formed directly on said p-type base layer so as to contact a top surface of said p-type base layer, wherein said indium-containing p-type nitride semiconductor layer has an indium mole fraction higher than the indium mole fraction of said p-type InGaN base layer; and

a base electrode formed over said indium-containing p-type nitride semiconductor layer.

- 91. **(New)** The nitride semiconductor structure according to claim 90, wherein said indium-containing p-type nitride semiconductor layer is p-type InGaN.
- 92. **(New)** The nitride semiconductor structure according to claim 91, wherein said p-type InGaN base layer has an indium mole fraction of 5 30%.
- 93. **(New)** The nitride semiconductor structure according to claim 90, wherein said p-type InGaN base layer has an indium mole fraction of 5 30%.
- 94. **(New)** The nitride semiconductor structure according to claim 90, further comprising a graded layer between said p-type base layer and said n-type collector layer, wherein said graded layer has an indium mole fraction that varies gradually.
- 95. **(New)** The nitride semiconductor structure according to claim 91, further comprising a graded layer between said p-type base layer and said n-type collector layer, wherein said graded layer has an indium mole fraction that varies gradually.
- 96. **(New)** The nitride semiconductor structure according to claim 90, wherein the base electrode is formed directly on said indium-containing p-type nitride semiconductor layer.
- 97. **(New)** The nitride semiconductor structure according to claim 90, wherein the indium-containing p-type nitride semiconductor layer has a thickness of between 1 and 1000 nm.
- 98. **(New)** The nitride semiconductor structure according to claim 90, wherein the indium-containing p-type nitride semiconductor layer has a thickness of about 100 nm.